MOTHER TERESA INSTITUTE OF SCIENCE & TECHNOLOGY
SATHUPALLY, KHAMMAM DIST, TELANGANA

Guidelines to prepare B.Tech Seminar Documentation

Font :
1. Chapter names - 16 TNR (bold) all caps
2. Headings - 14 TNR (bold) all caps
3. Subheadings - 14 TNR (bold) Title case
4. Sub-Subheadings - 12 TNR (bold) Title case
5. Body of Paper - 12 TNR
6. Text in Diagrams - 12 TNR (all lower case)
7. Diagrams/ Table headings/ Fig. Headings - 12' TNR Title case

(write figure name below the figure Ex: Fig 1.1,1.2…(figure 1.1 belongs to 1st chapter 1st figure)

(write Table name above the table Ex: Table1.1,1.2…(Table1.1 belongs to 1st chapter 1st table)

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TNR: Times New Roman

Spacing :
1. **2** Line Spacing between heading and body text
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3. New paragraph start with single tab.

Margins : Left **1.5'** Right **1.0'**
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Page numbers: **Position: Bottom, Middle**
1. Front Pages Small Roman numbers
   (Excluding title page, Certificate page, Acknowledgement page)
2. Body pages 1, 2, 3…..
3. Annexure I,II,III……
   (Separate for each Annexure)

Pages:- **Size: A4** paper **Color:** White

PREPARATION OF DOCUMENTATION

The sequence in which the Seminar Report should be arranged as follows and should be hard bounded.

Title page (color print)
College Certificate (color print)
Project Certificate (color print)
Institute Vision & Mission
Department Vision & Mission
PO Statements, PEO's, PSO's
Declaration
Acknowledgement
Contents
List of figures
List of tables
List of symbols & abbreviations
Abstract
Chapter-1: Introduction
Chapter-2: Literature Survey
Chapter-3: Proposed Methodology
Chapter-4: Result Analysis and Discussion
Chapter-5: Conclusion
Chapter-6: Future Scope of the Project
(A) Appendices [Continuation of lower-case Roman Numerals from (A)]
References

TOTAL NUMBER OF PAGES: **40 to 60.**

"CONTINUOUSLY VARIABLE TRANSMISSION (CVT)"

A Technical Seminar Report submitted in partial fulfillment of the requirements for the award of the degree of

BACHELOR OF TECHNOLOGY

In

Electronics & Communication Engineering

By

[Name(s) of the Student]

Under the Esteemed Guidance of

[Name of the Seminar Guide]

Designation

DEPARTMENT OF XXXXX ENGINEERING

MOTHER TERESA INSTITUTE OF SCIENCE AND TECHNOLOGY

Accredited By NAAC with '$\mathbf{A^+}$' Grade

Approved by AICTE, Govt.of Telangana & SBTET, Affiliated to JNTUH, Hyderabad.

Recognition under section 2(f) & 12(B) of the UGC Act,1956

Sanketika nagar, Sathupally-507303, Khammam(Dist), Telangana State.

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CERTIFICATE

This is to certify that the Technical Seminar entitled **"TITLE OF THE TECHNICAL SEMINAR"** is a bonafide work done by **STUDENT NAME (H.NO).** In partial fulfillment of the requirements for the award of the Degree of Bachelor of Technology in **BRANCH NAME** from Jawaharlal Nehru Technological University Hyderabad During the Academic Year 2023-2024.

Name of the Guide
Qualification

Name of HOD
Head of the Department
Qualification

Internal Examiner
Date:

ACKNOWLEDGEMENT

We are grateful to numerous individuals who contributed to the preparation of our Technical Seminar.

We wish to express our sincere and heart full gratitude to our Technical seminar guide **Name of the Guide, M.Tech** Designation, **Name of the Branch,** who encouragement and cooperation during the Technical seminar work.

We thank and deep sense of gratitude to **Name of the HOD Qualification.** Designation, BRANCH NAME, for their constant encouragement and cooperation during the Technical seminar work.

We would like to thank and express our gratitude to **Dr. Sk. Jakeer Hussain, M.Tech, Ph.D,** Dean Engineering, Mother Teresa Institute of Science & Technology for the support and encouragement during the completion of the Technical seminar.

We express our gratitude and utmost regards to **Dr. C. Hari Krishna** **M.E, Ph.D, M.I.E.E.E, MISTE** Principal, Mother Teresa Institute of Science & Technology for their constant support, encouragement during the completion of the Technical seminar.

We also thank the entire faculty members and fellow classmates who directly or indirectly helped us to complete this Technical seminar.

Name of the Student **Roll no**

DECLARATION

I hereby certify that the Technical seminar Report entitled **"Title of the Technical seminar"** under the guidance of **Name of the Guide, Qualification** is submitted in partial fulfillment of the requirements for the Award of the Degree of Bachelor of Technology in **BRANCH NAME**. This is a record of bonafide work carried by me and the results embodied in this Technical seminar Report have not been submitted to any other University or Institute for the Award of any other Degree.

Name of the Student **Roll No**

DATE:

Department of XXXXXX Engineering
Mother Teresa Institute of Science & Technology,
Sathupally.

INSTITUTE VISION

To be a state-of-the-art centre for learning with a social commitment transforming the youth into dynamic professionals.

INSTITUTE MISSION

IM_1: Foster unmatched excellence in professional education

IM_2: Provide quality eco-system to inspire learning aligned to needs.

IM_3: Inculcate ethical and moral values to groom good citizens.

IM_4: Involve in activities with team spirit and collaborations towards nation building.

DEPARTMENT VISION

To be recognized as a contributor of Mechanical Engineering proficiency and enable entrepreneurship, innovation, and values.

DEPARTMENT MISSION

DM_1: To train Stake holders on modeling and analysis software's for developing their computational capabilities as well as promoting studies and research works.

DM_2: Create awareness about the needs of mechanical industries through alumni and industry-institute interactions.

DM_3: To impart strong ethical values, lifelong learning and serve the society.

PROGRAMME EDUCATIONAL OBJECTIVES (PEOs)

PEO 1: Succeed in Mechanical engineering field and to pursue research endeavors with a solid foundation in basic sciences, engineering fundamentals and analytical skills.

PEO 2: Exhibit industry readiness with the state of the art in Mechanical and allied engineering for successful career.

PEO 3: Acquire lifelong learning skills, professional ethics, good communication capabilities and leadership qualities.

PROGRAM SPECIFIC OUTCOMES (PSOs)

PSO1: Identify, analyze and build manufacturing and thermal systems using fundamental principles and techniques.

PSO2: Use modeling and analysis software tools such as SOLIDWORKS, CFD, and ANSYS.

PSO3: Exhibit managerial and technical skills to work effectively in teams with ethics

PROGRAM OUTCOMES

Engineering Graduates will be able to:

1. **Engineering knowledge**: Apply the knowledge of mathematics, science, engineering fundamentals, and an engineering specialization to the solution of complex engineering problems.

2. **Problem analysis**: Identify, formulate, review research literature, and analyze complex engineering problems reaching substantiated conclusions using first principles of mathematics, natural sciences, and engineering sciences.

3. **Design/development of solutions**: Design solutions for complex engineering problems and design system components or processes that meet the specified needs with appropriate consideration for the public health and safety, and the cultural, societal, and environmental considerations.

4. **Conduct investigations of complex problems**: Use research-based knowledge and research methods including design of experiments, analysis and interpretation of data, and synthesis of the information to provide valid conclusions.

5. **Modern tool usage**: Create, select, and apply appropriate techniques, resources, and modern engineering and IT tools including prediction and modeling to complex engineering activities with an understanding of the limitations.

6. **The engineer and society**: Apply reasoning informed by the contextual knowledge to assess societal, health, safety, legal and cultural issues and the consequent responsibilities relevant to the professional engineering practice.

7. **Environment and sustainability**: Understand the impact of the professional engineering solutions in societal and environmental contexts, and demonstrate the knowledge of, and need for sustainable development.

8. **Ethics**: Apply ethical principles and commit to professional ethics and responsibilities and norms of the engineering practice.

9. **Individual and team work**: Function effectively as an individual, and as a member or leader in diverse teams, and in multidisciplinary settings.

10. **Communication**: Communicate effectively on complex engineering activities with the engineering community and with society at large, such as, being able to comprehend and write effective reports and design documentation, make effective presentations, and give and receive clear instructions.

11. **Project management and finance**: Demonstrate knowledge and understanding of the engineering and management principles and apply these to one's own work, as a member and leader in a team, to manage projects and in multidisciplinary environments.

12. **Life-long learning**: Recognize the need for, and have the preparation and ability to engage in independent and life-long learning in the broadest context of technological change.

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LIST OF ABBREVIATIONS AND SYMBOLS

VLSI	:	Very Large Scale Integration
FPGA	:	Field Programmable
Logic Controller DSP	:	Digital Signal Processing
x[n]	:	Filter Input Signal
y[n]	:	Filter Output Signal
δ[n]	:	Delta Function
h[n]	:	Filter Impulse Response
H[n]	:	Transfer Function
*	:	Convolution Operator

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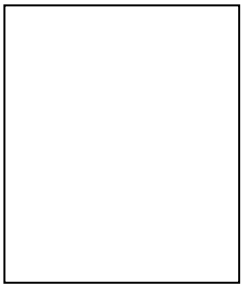

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Father name:

Roll. No :

Date of Birth :

Nationality :

Communication Address:

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Mandal **:**

District **:**

Pin code **:**

Ph.no **:**

E-mail **:**

Permanent Address:

Town/village **:**

Mandal **:**

District **:**

Pin code **:**

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E-mail **:**

Qualifications :

Technical Skills :

Area of Interest :

Signature